

Description

The DMP3028LK3 uses advanced trench technology

to provide excellent R_{DS(ON)}, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

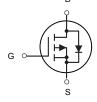


TO-252-2L

General Features

 $V_{DS} = -30V I_{D} = -40A$

 $R_{DS(ON)}$ < 23 m Ω @ V_{GS} =10V



P-Channel MOSFET

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
DMP3028LK3	TO-252-2L	HXY MOSFET	2500

Absolute Maximum Ratings (T_c=25°Cunless otherwise noted)

Symbol	Parameter Ratin		Units		
VDS	Drain-Source Voltage	-30	V		
VGS	Gate-Source Voltage	±20	٧		
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	nin Current, V _{GS} @ 10V ¹ -40			
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	-25	А		
IDM	Pulsed Drain Current ²	-70	А		
P _D @T _C =25°C	Total Power Dissipation ⁴	34.7	W		
TSTG	Storage Temperature Range	-55 to 150	°C		
TJ	Operating Junction Temperature Range	-55 to 150	°C		
ReJA	Thermal Resistance Junction-ambient ¹	62	°C/W		
R₀JC	Thermal Resistance Junction-Case ¹	3.6 °C/W			



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.022		V/°C	
D 64	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-15A		18	23	mΩ	
RDS(ON)	Static Dialii-Source On-Resistance	V _{GS} =-4.5V , I _D =-10A		37	44	1112.2	
$V_{GS(th)}$	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =-250uA	-1.0		-2.5	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS-VDS , ID250UA		4.6	1	mV/°C	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =25°C			-1	uA	
IDSS		V _{DS} =-24V , V _{GS} =0V , T _J =55°C	V _{DS} =-24V , V _{GS} =0V , T _J =55°C		-5	uA	
Igss	Gate-Source Leakage Current	$V_{GS}=\pm 20V$, $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-10A		5		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		13		Ω	
Qg	Total Gate Charge (-4.5V)			12.5		nC	
Q _{gs}	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-15A		5.4			
Q _{gd}	Gate-Drain Charge			5			
T _{d(on)}	Turn-On Delay Time			4.4			
Tr	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_{G} =3.3 Ω ,		11.2	1	ns	
T _{d(off)}	Turn-Off Delay Time	I _D =-15A		34	-		
Tf	Fall Time			18			
Ciss	Input Capacitance			1345			
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		194		pF	
Crss	Reverse Transfer Capacitance			158			
Is	Continuous Source Current ^{1,5}	Vo=Vo=OV Force Current			-40	Α	
I _{SM}	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			-75	Α	
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1.2	V	
t _{rr}	Reverse Recovery Time	IF=-15A , dI/dt=100A/μs ,		12.4		nS	
Qrr	Reverse Recovery Charge	T _J =25°C		5		nC	

Note:

^{1.} The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

^{2.}The data tested by pulsed , pulse width $\,\leq\,300\text{us}$, duty cycle $\,\leq\,2\%$

^{3.} The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V, L=0.1mH, I_{AS}=-38A

^{4.} The power dissipation is limited by 150 $^{\circ}\text{C}\,$ junction temperature

^{5.} The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

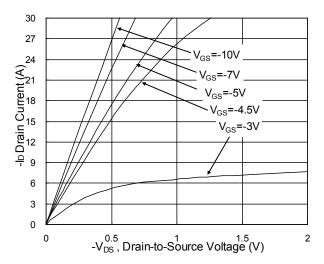


Fig.1 Typical Output Characteristics

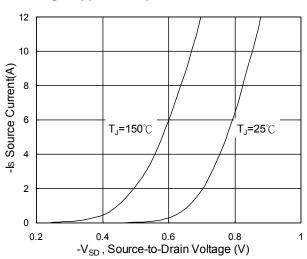


Fig.3 Forward Characteristics of Reverse

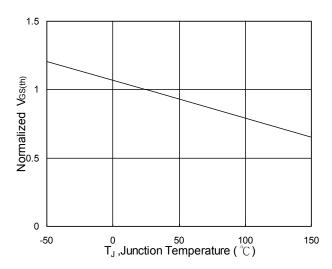


Fig.5 Normalized V_{GS(th)} v.s T_J

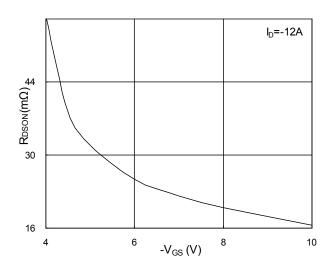


Fig.2 On-Resistance v.s Gate-Source

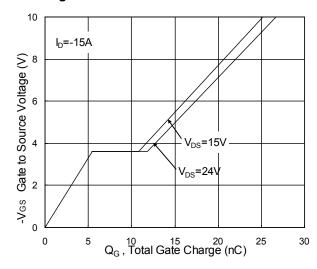


Fig.4 Gate-Charge Characteristics

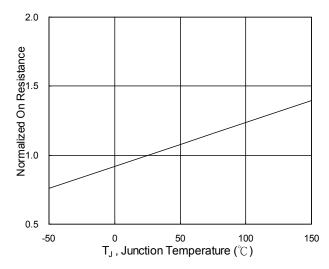
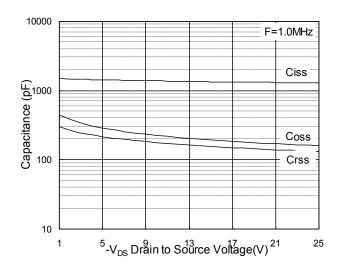


Fig.6 Normalized R_{DSON} v.s T_J



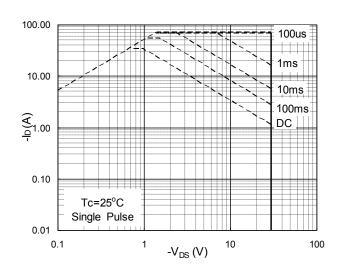


Fig.7 Capacitance

Fig.8 Safe Operating Area

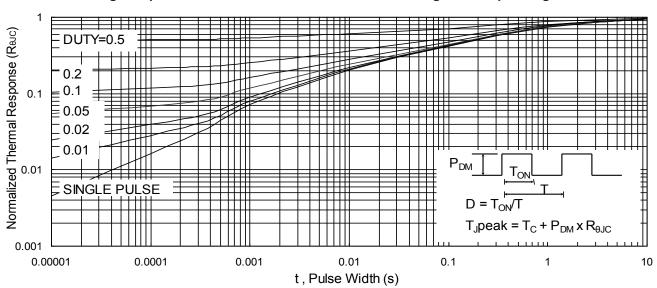


Fig.9 Normalized Maximum Transient Thermal Impedance

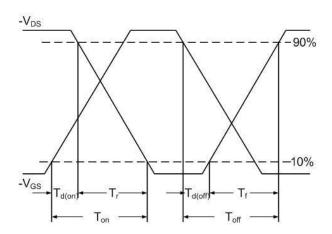


Fig.10 Switching Time Waveform

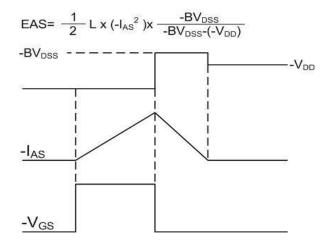
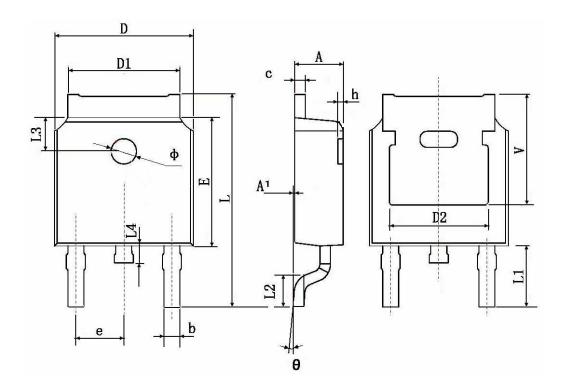


Fig.11 Unclamped Inductive Switching Waveform



TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
А	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	0.483 TYP.		0.190 TYP.		
E	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3	1.600 TYP.		0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350 TYP.		0.211 TYP.		

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